

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (currently amended) A nozzle assembly for directing flow of a fluid across one or more semiconductor device cutting blades, comprising:

[[-]] one or more nozzles configured to protrude toward a cutting blade for cutting a semiconductor device; and

[[-]] a channel formed in each of the one or more nozzles, the channel being configured to at least partially surround the cutting blade, so as to simultaneously direct flow of a fluid onto the cutting edge of the cutting blade and onto the sides of the cutting blade.

2. (currently amended) The nozzle assembly of claim 1, wherein the one or more nozzles are affixed to and in fluid communication with a pipe member, so as to direct flow of the fluid from the pipe member through the one or more channels.

3. (currently amended) The nozzle assembly of claim 1, wherein the ~~nozzle is one or~~ more nozzles are oriented generally toward the semiconductor device while the cutting blade is dicing the semiconductor device.

4. (currently amended) The nozzle assembly of claim 1, wherein the one or more nozzles comprises a plurality of nozzles ~~are present and configured to protrude toward a cutting blade for cutting a semiconductor device, each nozzle having a channel that is configured to at least partially surround the cutting blade, so as to simultaneously direct flow of a fluid onto the cutting edge of the cutting blade and onto the sides of the cutting blade.~~

5. (withdrawn) A dicing apparatus comprising at least one cutting blade to which cooling fluid is provided through a nozzle, wherein the nozzle as claimed in claim 1 is used.
6. (withdrawn) A dicing apparatus as claimed in claim 5, comprising a plurality of cutting blades positioned parallel to each other, each cutting blade being provided with a nozzle directed towards the cutting blade for the provision of the cooling fluid.
7. (withdrawn) A dicing apparatus as claimed in claim 6, wherein the cutting blades are mutually separated by spacers.
8. (withdrawn) Use of the sawing apparatus as claimed in claim 5 for the dicing of semiconductor devices.
9. (withdrawn) Use as claimed in claim 8, wherein the semiconductor devices is packaged including a leadframe and an encapsulation, and wherein the dicing dices through the encapsulation and the leadframe.
10. (new) The nozzle assembly of claim 2, wherein the pipe member comprises an inlet at one end and a fluid passage extending from the inlet to an opening in the side of the pipe member.
11. (new) The nozzle assembly of claim 10, wherein the one or more nozzles are connected to the pipe member through the opening in the side of the pipe member.
12. (new) The nozzle assembly of claim 1, wherein the channel withholds the fluid.
13. (new) The nozzle assembly of claim 12, wherein each of the one or more nozzles includes a blade receiving portion and a fluid passage portion, wherein the blade receiving portion includes the channel, and wherein the fluid passage portion includes a through slot that directs fluid from the pipe member to the channel of the blade receiving portion.

14. (new) The nozzle assembly of claim 13, wherein the slot include an inlet for receiving the fluid from the pipe member and an outlet for distributing the fluid to the channel of the blade receiving portion.

15. (new) The nozzle assembly of claim 13, wherein each of the one or more nozzles includes a cavity, which is between the inlet and the pipe member.